

High-Speed CMOS Logic BCD-to-Decimal Decoders (1 of 10)

Features

- Buffered Inputs and Outputs
- Typical Propagation Delay: 12ns at $V_{CC} = 5V$, $C_L = 15pF$, $T_A = 25^\circ C$
- Fanout (Over Temperature Range)
 - Standard Outputs 10 LSTTL Loads
 - Bus Driver Outputs 15 LSTTL Loads
- Wide Operating Temperature Range ... -55°C to 125°C
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- HC Types
 - 2V to 6V Operation
 - High Noise Immunity: $N_{IL} = 30\%$, $N_{IH} = 30\%$ of V_{CC} at $V_{CC} = 5V$
- HCT Types
 - 4.5V to 5.5V Operation
 - Direct LSTTL Input Logic Compatibility, $V_{IL} = 0.8V$ (Max), $V_{IH} = 2V$ (Min)
 - CMOS Input Compatibility, $I_I \leq 1\mu A$ at V_{OL}, V_{OH}

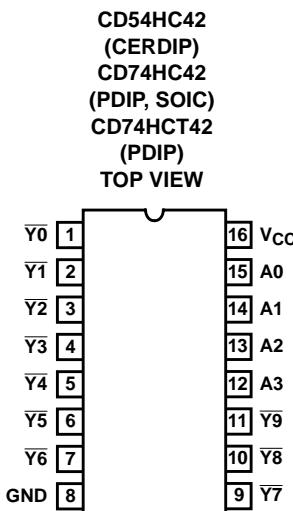
Description

The 'HC42 and CD74HCT42 BCD-to-Decimal Decoders utilize silicon-gate CMOS technology to achieve operating speeds similar to LSTTL decoders with the low power consumption of standard CMOS integrated circuits. These devices have the capability of driving 10 LSTTL loads and are compatible with the standard LS logic family. One of ten outputs (low on select) is selected in accordance with the BCD input. Non-valid BCD inputs result in none of the outputs being selected (all outputs are high).

Ordering Information

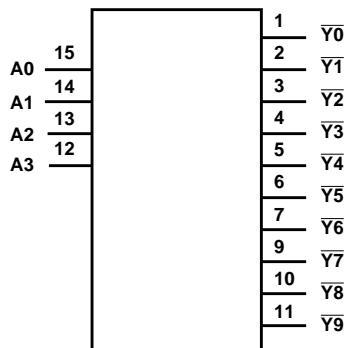
PART NUMBER	TEMP. RANGE (°C)	PACKAGE
CD54HC42F3A	-55 to 125	16 Ld CERDIP
CD74HC42E	-55 to 125	16 Ld PDIP
CD74HC42M	-55 to 125	16 Ld SOIC
CD74HCT42E	-55 to 125	16 Ld PDIP

Pinout



CD54HC42, CD74HC42, CD74HCT42

Functional Diagram



TRUTH TABLE

INPUTS				OUTPUTS									
A3	A2	A1	A0	\bar{Y}_0	\bar{Y}_1	\bar{Y}_2	\bar{Y}_3	\bar{Y}_4	\bar{Y}_5	\bar{Y}_6	\bar{Y}_7	\bar{Y}_8	\bar{Y}_9
L	L	L	L	L	H	H	H	H	H	H	H	H	H
L	L	L	H	H	L	H	H	H	H	H	H	H	H
L	L	H	L	H	H	L	H	H	H	H	H	H	H
L	L	H	H	H	H	H	L	H	H	H	H	H	H
L	H	L	L	H	H	H	H	L	H	H	H	H	H
L	H	L	H	H	H	H	H	H	L	H	H	H	H
L	H	H	L	H	H	H	H	H	H	L	H	H	H
L	H	H	H	H	H	H	H	H	H	H	L	H	H
H	L	L	L	H	H	H	H	H	H	H	H	H	L
H	L	L	H	H	H	H	H	H	H	H	H	H	L
H	L	H	L	H	H	H	H	H	H	H	H	H	H
H	L	H	H	H	H	H	H	H	H	H	H	H	H
H	H	L	L	H	H	H	H	H	H	H	H	H	H
H	H	L	H	H	H	H	H	H	H	H	H	H	H
H	H	H	L	H	H	H	H	H	H	H	H	H	H
H	H	H	H	H	H	H	H	H	H	H	H	H	H

H = High Voltage Level, L = Low Voltage Level

CD54HC42, CD74HC42, CD74HCT42

Absolute Maximum Ratings

DC Supply Voltage, V _{CC}	-0.5V to 7V
DC Input Diode Current, I _{IK}		
For V _I < -0.5V or V _I > V _{CC} + 0.5V	±20mA
DC Output Diode Current, I _{OK}		
For V _O < -0.5V or V _O > V _{CC} + 0.5V	±20mA
DC Output Source or Sink Current per Output Pin, I _O		
For V _O > -0.5V or V _O < V _{CC} + 0.5V	±25mA
DC V _{CC} or Ground Current, I _{CC} or I _{GND}	±50mA

Thermal Information

Thermal Resistance (Typical, Note 1)	θ _{JA} (°C/W)
E (PDIP) Package
M (SOIC) Package
Maximum Junction Temperature 150°C
Maximum Storage Temperature Range -65°C to 150°C
Maximum Lead Temperature (Soldering 10s) 300°C
(SOIC - Lead Tips Only)	

Operating Conditions

Temperature Range (T _A)	-55°C to 125°C
Supply Voltage Range, V _{CC}		
HC Types2V to 6V
HCT Types45V to 5.5V
DC Input or Output Voltage, V _I , V _O	0V to V _{CC}
Input Rise and Fall Time		
2V	1000ns (Max)
4.5V	500ns (Max)
6V	400ns (Max)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. The package thermal impedance is calculated in accordance with JESD 51-7.

DC Electrical Specifications

PARAMETER	SYMBOL	TEST CONDITIONS		V _{CC} (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS	
		V _I (V)	I _O (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX		
HC TYPES													
High Level Input Voltage	V _{IH}	-	-	2	1.5	-	-	1.5	-	1.5	-	V	
				4.5	3.15	-	-	3.15	-	3.15	-	V	
				6	4.2	-	-	4.2	-	4.2	-	V	
Low Level Input Voltage	V _{IL}	-	-	2	-	-	0.5	-	0.5	-	0.5	V	
				4.5	-	-	1.35	-	1.35	-	1.35	V	
				6	-	-	1.8	-	1.8	-	1.8	V	
High Level Output Voltage CMOS Loads	V _{OH}	V _{IH} or V _{IL}	-0.02	2	1.9	-	-	1.9	-	1.9	-	V	
			-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V	
			-0.02	6	5.9	-	-	5.9	-	5.9	-	V	
High Level Output Voltage TTL Loads			-	-	-	-	-	-	-	-	-	V	
			-4	4.5	3.98	-	-	3.84	-	3.7	-	V	
			-5.2	6	5.48	-	-	5.34	-	5.2	-	V	
Low Level Output Voltage CMOS Loads	V _{OL}	V _{IH} or V _{IL}	0.02	2	-	-	0.1	-	0.1	-	0.1	V	
			0.02	4.5	-	-	0.1	-	0.1	-	0.1	V	
			0.02	6	-	-	0.1	-	0.1	-	0.1	V	
Low Level Output Voltage TTL Loads			-	-	-	-	-	-	-	-	-	V	
			4	4.5	-	-	0.26	-	0.33	-	0.4	V	
			5.2	6	-	-	0.26	-	0.33	-	0.4	V	
Input Leakage Current	I _I	V _{CC} or GND	-	6	-	-	±0.1	-	±1	-	±1	µA	
Quiescent Device Current	I _{CC}	V _{CC} or GND	0	6	-	-	8	-	80	-	160	µA	

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DC Electrical Specifications (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS		V _{CC} (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
		V _I (V)	I _O (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
HCT TYPES												
High Level Input Voltage	V _{IH}	-	-	4.5 to 5.5	2	-	-	2	-	2	-	V
Low Level Input Voltage	V _{IL}	-	-	4.5 to 5.5	-	-	0.8	-	0.8	-	0.8	V
High Level Output Voltage CMOS Loads	V _{OH}	V _{IH} or V _{IL}	-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
High Level Output Voltage TTL Loads			-4	4.5	3.98	-	-	3.84	-	3.7	-	V
Low Level Output Voltage CMOS Loads	V _{OL}	V _{IH} or V _{IL}	0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads			4	4.5	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I _I	V _{CC} and GND	0	5.5	-		±0.1	-	±1	-	±1	µA
Quiescent Device Current	I _{CC}	V _{CC} or GND	0	5.5	-	-	8	-	80	-	160	µA
Additional Quiescent Device Current Per Input Pin: 1 Unit Load	ΔI _{CC} (Note 2)	V _{CC} -2.1	-	4.5 to 5.5	-	100	360	-	450	-	490	µA

NOTE:

2. For dual-supply systems theoretical worst case (V_I = 2.4V, V_{CC} = 5.5V) specification is 1.8mA.

HCT Input Loading Table

INPUT	UNIT LOADS
All	1

NOTE: Unit Load is ΔI_{CC} limit specified in DC Electrical Table, e.g. 360µA max at 25°C.

Switching Specifications Input t_r, t_f = 6ns

PARAMETER	SYMBOL	TEST CONDITIONS	V _{CC} (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
HC TYPES											
Propagation Delay, Input to Y (Figure 1)	t _{PLH} , t _{PHL}	C _L = 50pF	2	-	-	150	-	190	-	225	ns
			4.5	-	-	30	-	38	-	45	ns
			6	-	-	26	-	33	-	38	ns
Any Input to \bar{Y}	t _{PLH} , t _{PHL}	C _L = 15pF	5	-	12	-	-	-	-	-	ns
Output Transition Time (Figure 1)	t _{TLH} , t _{THL}	C _L = 50pF	2	-	-	75	-	95	-	110	ns
			4.5	-	-	15	-	19	-	22	ns
			6	-	-	13	-	16	-	19	ns
Input Capacitance	C _{IN}	-	-	-	-	10	-	10	-	10	pF

Switching Specifications Input $t_r, t_f = 6\text{ns}$ (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS	V_{CC} (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
Power Dissipation Capacitance (Notes 3, 4)	C_{PD}	-	5	-	65	-	-	-	-	-	pF
HCT TYPES											
Propagation Delay, Input to Y (Figure 2)	t_{PLH}, t_{PHL}	$C_L = 50\text{pF}$	4.5	-	-	35	-	44	-	53	ns
Any Input to \bar{Y}	t_{PLH}, t_{PHL}	$C_L = 15\text{pF}$	5	-	14	-	-	-	-	-	ns
Output Transition Time (Figure 2)	t_{TLH}, t_{THL}	$C_L = 50\text{pF}$	4.5	-	-	15	-	19	-	22	ns
Input Capacitance	C_{IN}	-	-	-	-	10	-	10	-	10	pF
Power Dissipation Capacitance (Notes 3, 4)	C_{PD}	-	5	-	70	-	-	-	-	-	pF

NOTES:

3. C_{PD} is used to determine the dynamic power consumption, per package.
4. $P_D = V_{CC}^2 f_i (C_{PD} + C_L)$ where: f_i = Input Frequency, C_L = Output Load Capacitance, V_{CC} = Supply Voltage.

Test Circuits and Waveforms

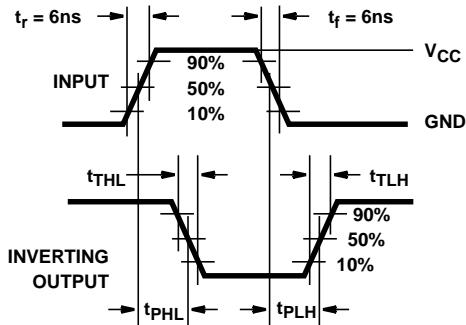


FIGURE 1. HC AND HCU TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

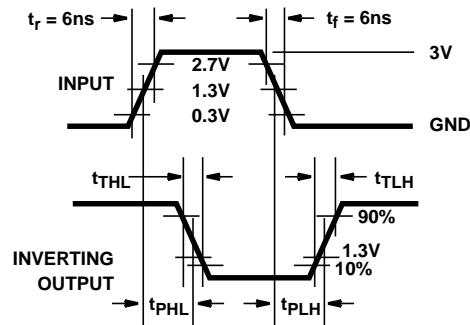


FIGURE 2. HCT TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC